

REMARKS

Claims 17-20 remain allowed. Claims 1-16 & 21 were rejected under 35 U.S.C. 112, first paragraph. Examiner asserted that claim 1 has been amended to recite the formation of a metal layer on the **plate**, but the originally-filed specification does not support the formation of any and all metal layers on the **substrate** but only those facilitating separation of the **plate** and the organic resin.

In response, Applicants respectfully point out that the above amendment to claim 1 actually can be supported by the specification, at least because

1) the plate is not the substrate, as seen from claim 1 recited and marked below, while the metal layer is formed on the plate but not on the substrate,

“Claim 1. A manufacturing method ..., comprising the following steps:

providing a substrate;

forming a reflective layer on the substrate;

applying a radiation-setting resin on the reflective layer;

***providing a plate** having a flat surface;*

*forming a **metal layer** on the **plate**;”*

2) [0017]/line 1 of the specification describes “a poorly-adhesive **metal layer** can be formed on the **plate**”, and

3) [0042] describes “a poorly-adhesive **metal layer** 220 is formed on a **plate** 204” (lines 1-2) and mentions in lines 5-7 that the material of the poorly-adhesive **metal layer** 220 can be selected from **metal materials** including gold, silver, aluminum, chromium, platinum, nickel, copper, palladium, silicon and the alloy thereof.

Accordingly, Applicants submit that the above amendment to claim 1 is supported by the originally-filed specification, and therefore respectfully request withdrawal of the rejections to claims 1-16 & 21 under 35 U.S.C. 112.

CONCLUSION

For at least the foregoing reasons, it is believed that all the pending claims 1-16 & 21 of the present application are in proper condition for allowance like claims 17-20 are. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted,
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